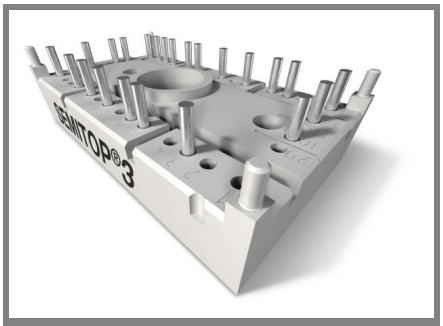
SK55GARL065E



SEMITOP® 3

IGBT Module

SK55GARL065E

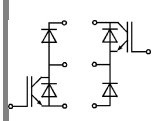
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N-channel homogeneous silicon structure (NPT-Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence

Typical Applications*

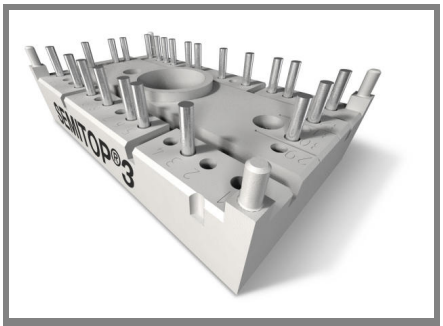
- Switching (not for linear use
- Switched mode power supplies
- UPS
- Double PFC
- Multilevel inverter



GARL-E

Absolute Maximum Ratings			T_s = 25 °C, unless otherwise specified	
Symbol	**Conditions**		**Values**	**Units**
IGBT				
V_{CES}	T_j = 25 °C		600	V
I_C	T_j = 125 °C	T_s = 25 °C	54	A
		T_s = 80 °C	40	A
I_{CRM}	I_{CRM}= 2 x I_{Cnom}		120	A
V_{GES}			± 20	V
t_{psc}	V_{CC} = 300 V; $V_{GE} \leq$ 20 V; V_{CES} < 600 V	T_j = 125 °C	10	µs
Inverse Diode				
I_F	T_j = 150 °C	T_s = 25 °C	36	A
		T_s = 80 °C	24	A
I_{FRM}	I_{FRM}= 2 x I_{Fnom}			A
I_{FSM}	t_p = 10 ms; half sine wave	T_j = 150 °C	200	A
Freewheeling Diode				
I_F	T_j = 150 °C	T_s = 25 °C	64	A
		T_s = 80 °C	48	A
I_{FRM}	I_{FRM}= 2 x I_{Fnom}			A
I_{FSM}	t_p = 10 ms; half sine wave	T_j = 150 °C	440	A
Module				
$I_{t(RMS)}$				A
T_{vj}			-40 ... +150	°C
T_{stg}			-40 ... +125	°C
V_{isol}	AC, 1 min.		2500	V

Characteristics			T_s = 25 °C, unless otherwise specified			
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
IGBT						
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 1,4 mA		3	4	5	V
I_{CES}	V_{GE} = 600 V, V_{CE} = V_{CES}	T_j = 25 °C			0,0044	mA
I_{GES}	V_{CE} = 0 V, V_{GE} = 20 V	T_j = 25 °C			240	nA
V_{CE0}		T_j = 25 °C		1,2	1,3	V
		T_j = 125 °C		1,1	0,9	V
r_{CE}	V_{GE} = 15 V	T_j = 25°C			12	mΩ
		T_j = 125°C			22	mΩ
$V_{CE(sat)}$	I_{Cnom} = 60 A, V_{GE} = 15 V	T_j = 25°C$_{chiplev.}$		1,7	2	V
		T_j = 125°C$_{chiplev.}$		2,2	2,2	V
C_{ies}	V_{CE} = 25, V_{GE} = 0 V	f = 1 MHz		3,2		nF
C_{oes}				0,3		nF
C_{res}				0,18		nF
Q_G	V_{GE}=0 ... 20 V			375		nC
$t_{d(on)}$	R_{Gon} = 16 Ω	V_{CC} = 300V		60	80	ns
t_r		I_C= 40A		30	40	ns
E_{on}		T_j = 125 °C		1,1		mJ
$t_{d(off)}$	R_{Goff} = 16 Ω	V_{GE}= ±15V		220	280	ns
t_f				20	26	ns
E_{off}				0,76		mJ
$R_{th(j-s)}$	per IGBT				0,85	K/W



SEMITOP® 3

IGBT Module

SK55GARL065E

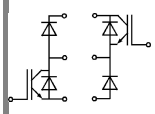
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N-channel homogeneous silicon structure (NPT-Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence

Typical Applications*

- Switching (not for linear use
- Switched mode power supplies
- UPS
- Double PFC
- Multilevel inverter



GARL-E

Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Units**
Inverse Diode						
$V_F = V_{EC}$	I_{Fnom} = 25 A; V_{GE} = 0 V	T_j = 25 °$C_{chiplev.}$		1,45	1,7	V
		T_j = 125 °$C_{chiplev.}$		1,4	1,75	V
V_{F0}		T_j = 125 °C		0,85	0,9	V
r_F		T_j = 125 °C		22	32	mΩ
I_{RRM}	I_F = 50 A	T_j = 125 °C		57		A
Q_{rr}	di/dt = -2400 A/µs			4,6		µC
E_{rr}	V_{CC}=300V			0,9		mJ
$R_{th(j-s)D}$	per diode				1,7	K/W
Freewheeling diode						
$V_F = V_{EC}$	I_{Fnom} = 50 A; V_{GE} = 0 V	T_j = 25 °$C_{chiplev.}$		1,45	1,7	V
		T_j = 125 °$C_{chiplev.}$		1,4	1,75	V
V_{F0}		T_j = 125 °C		0,85	0,9	V
r_F		T_j = 125 °C		11	16	V
I_{RRM}	I_F = 50 A	T_j = 125 °C		30		A
Q_{rr}	di/dt = -800 A/µs			3,6		µC
E_{rr}	V_R=300V			0,95		mJ
$R_{th(j-s)D}$	per diode				1,1	K/W
M_s	to heat sink		2,25		2,5	Nm
w				30		g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

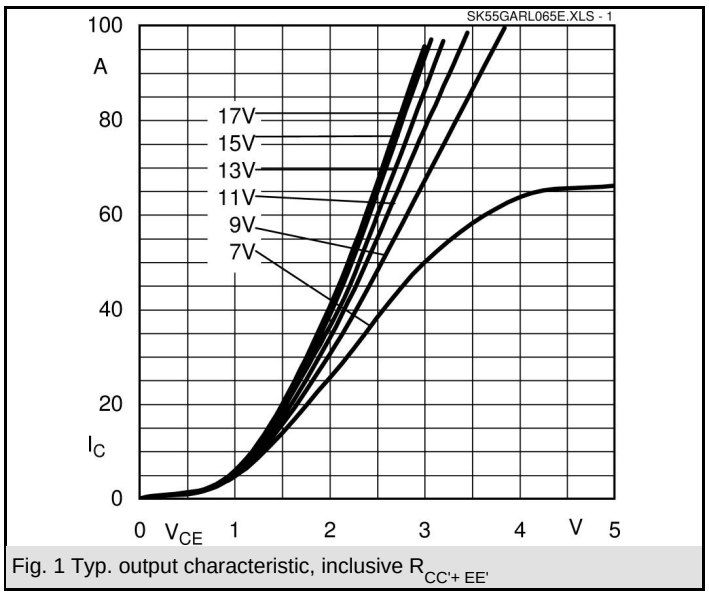


Fig. 1 Typ. output characteristic, inclusive $R_{CC'+ EE'}$

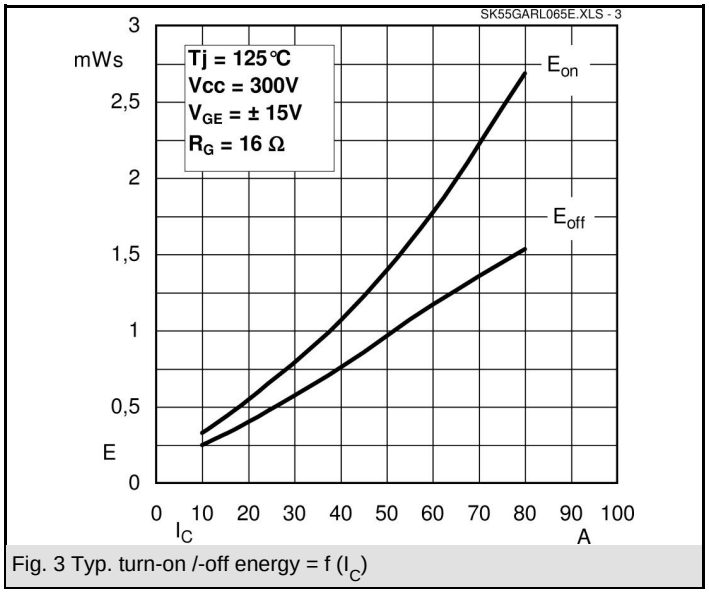


Fig. 3 Typ. turn-on /-off energy = f (I_C)

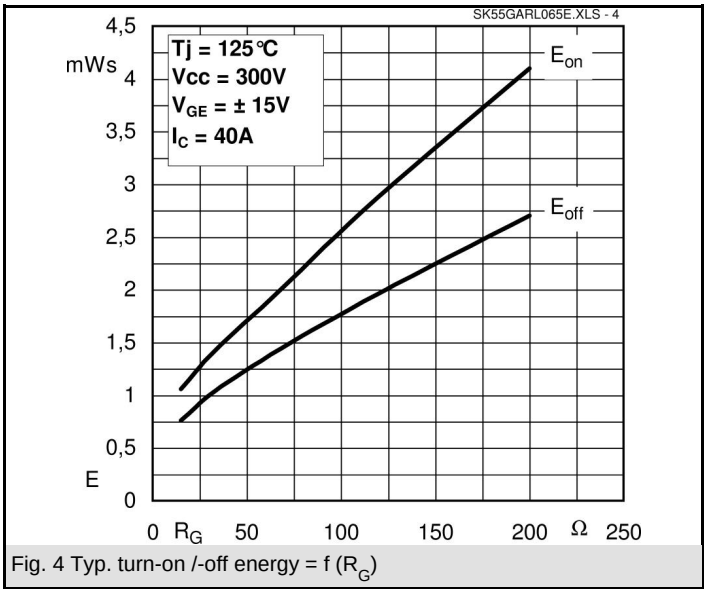


Fig. 4 Typ. turn-on /-off energy = f (R_G)

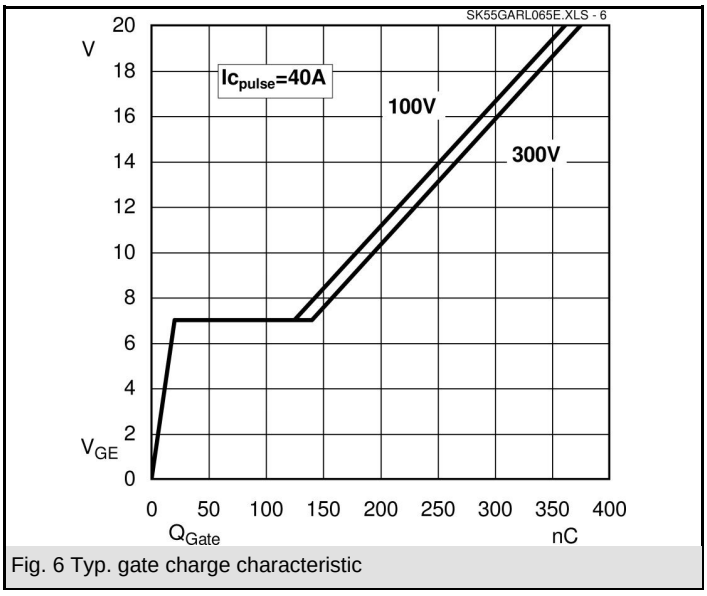


Fig. 6 Typ. gate charge characteristic

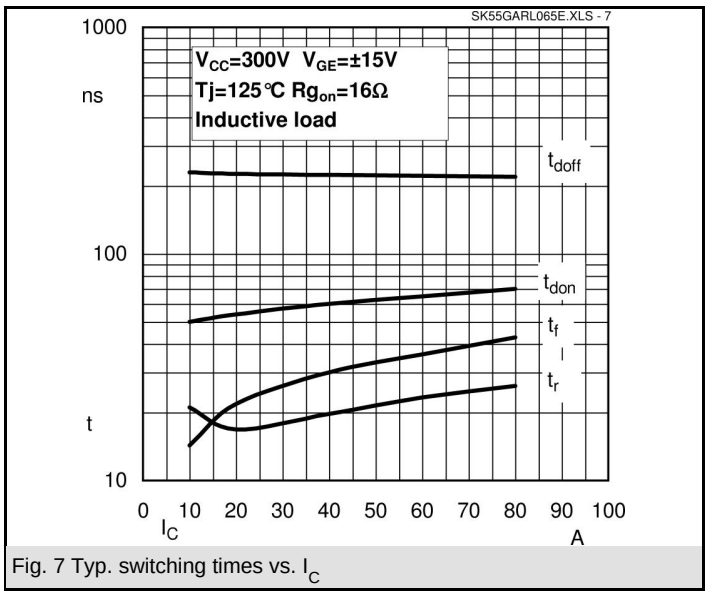


Fig. 7 Typ. switching times vs. I_C

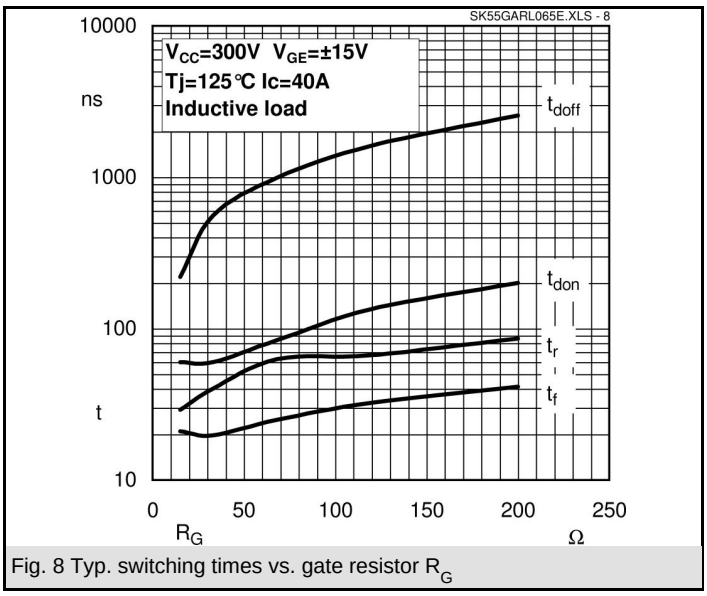


Fig. 8 Typ. switching times vs. gate resistor R_G

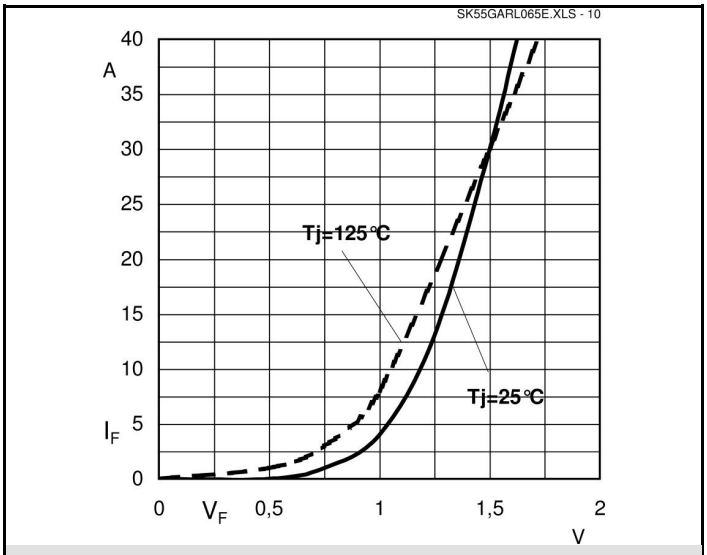
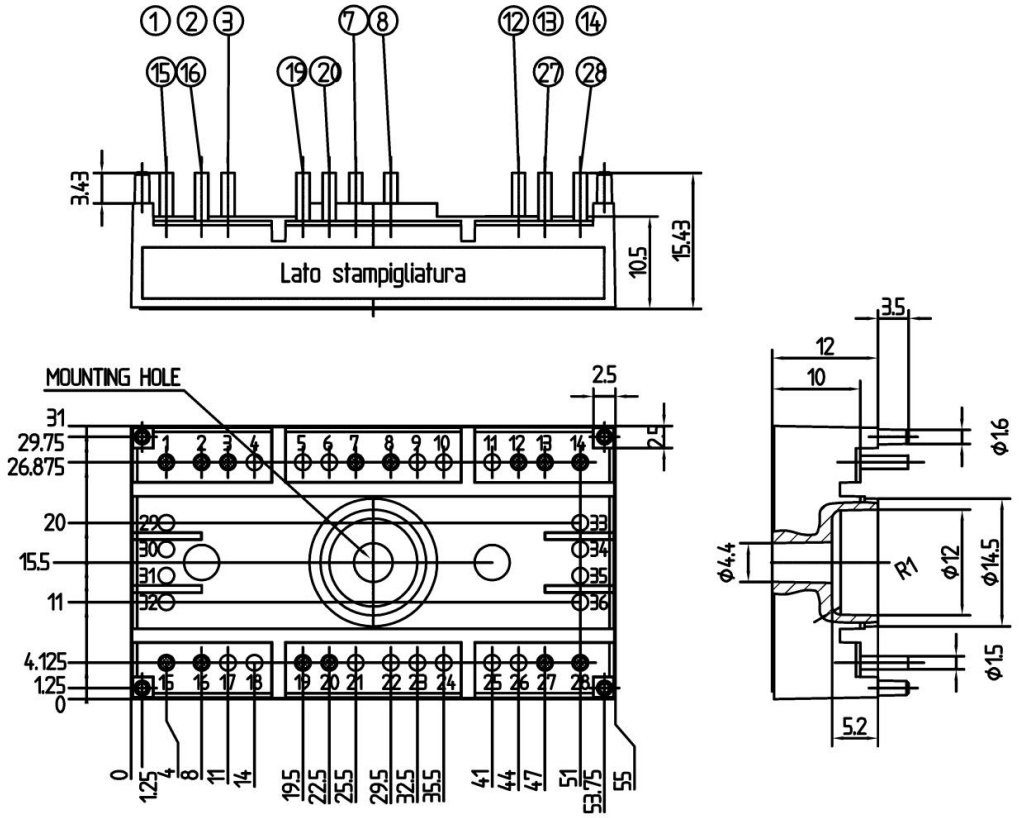
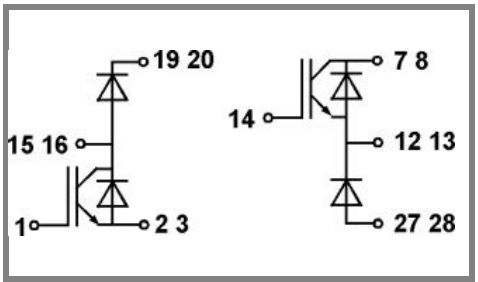


Fig. 10 CAL diode forward characteristic

UL recognized file no. E 63 532



Case T55 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T55 GARL-E

